

SIGNAL MEASUREMENT APPARATUS AND METHOD

Abstract of the Disclosure

Ground bounce measurement circuitry, integrated circuit packaging, memory
5 circuit modules, circuit cards, and systems, and methods to form, assemble, and use
them are provided. A circuit combination is disclosed which includes an integrated
circuit and measurement circuit, constructed so that each may be supported by a
single substrate, or enclosed within a single integrated circuit package. The
integrated circuit includes a test domain having a test voltage, and a reference
10 domain having a reference voltage. The measurement circuit is operatively
connected to the reference domain and the test domain to measure the ground
bounce voltage, which is the difference between the test voltage and the reference
voltage. The measured value of the ground bounce voltage can then be acquired by
a data acquisition system for later recall, or made immediately available for
15 observation using instrumentation outside of the substrate or integrated circuit
package environment.

"Express Mail" mailing label number: EL873860594US

Date of Deposit: August 30, 2001

This paper or fee is being deposited on the date indicated above with
the United States Postal Service pursuant to 37 CFR 1.10, and is
addressed to the Commissioner for Patents, Box Patent Application,
Washington, D.C. 20231.